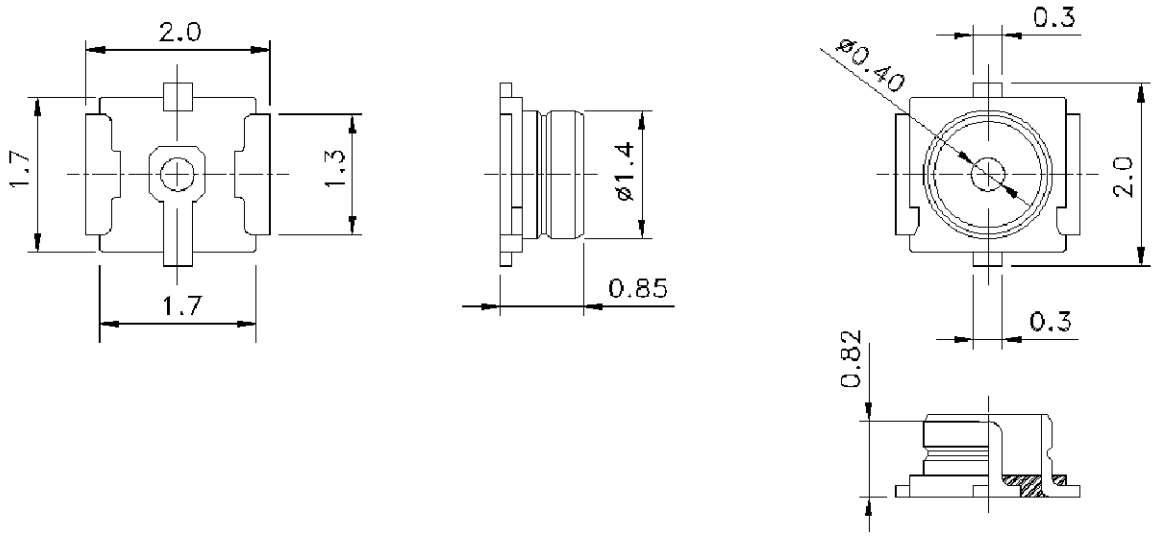
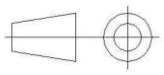
PAGE **1/4**	ISSUE **1424B**	SERIES **MML**	PART NUMBER **R302152000**



All dimensions are in mm.



COMPONENTS	MATERIALS	PLATING (µm)
Body	**BRONZE**	**GOLD**
Center contact	**BRASS**	**GOLD**
Outer contact		
Insulator	**LCP**	
Gasket		
Others parts		
-	-	-
-	-	-

PACKAGING

Standard	Unit	Other
5000	**Contact us**	**Contact us**

ELECTRICAL CHARACTERISTICS

Impedance			**50**	Ω
Frequency			**0-6**	GHz
VSWR	**1.35**	**+**	**0.0000**	x F(GHz) Maxi
Insertion loss			**NA**	√F(GHz) dB Maxi
RF leakage		- (	**NA**	- F(GHz)) dB Maxi
Voltage rating			**150**	Veff Maxi
Dielectric withstanding voltage			**200**	Veff mini
Insulation resistance			**500**	MΩ mini

MECHANICAL CHARACTERISTICS

Center contact retention		
Axial force – Mating End	**NA**	N mini
Axial force – Opposite end	**NA**	N mini
Torque	**NA**	N.cm mini
Recommended torque		
Mating	**NA**	N.cm
Panel nut	**NA**	N.cm
Mating life	**30**	Cycles mini
Weight	**0.0200**	g

ENVIRONMENTAL

Operating temperature	**-40/+90**	°C
Hermetic seal	**NA**	Atm.cm3/s
Panel leakage	**NA**	

SPECIFICATION

OTHER CHARACTERISTICS

Assembly instruction:

Others:

SOLDER PROCEDURE

1. Deposit solder paste (Sn Ag4 Cu0.5) on solder pads / mounting area by screen printing application. We recommend a low residue flux. We advise a thickness of 150 micron (5.850 microinch). Verify that the edges of the pads are clean.

2. Place the component on the mounting area with a pick & place machine.
   A video camera is recommended for a good positioning of the component.
   Adhesive agents must not be used on the component.

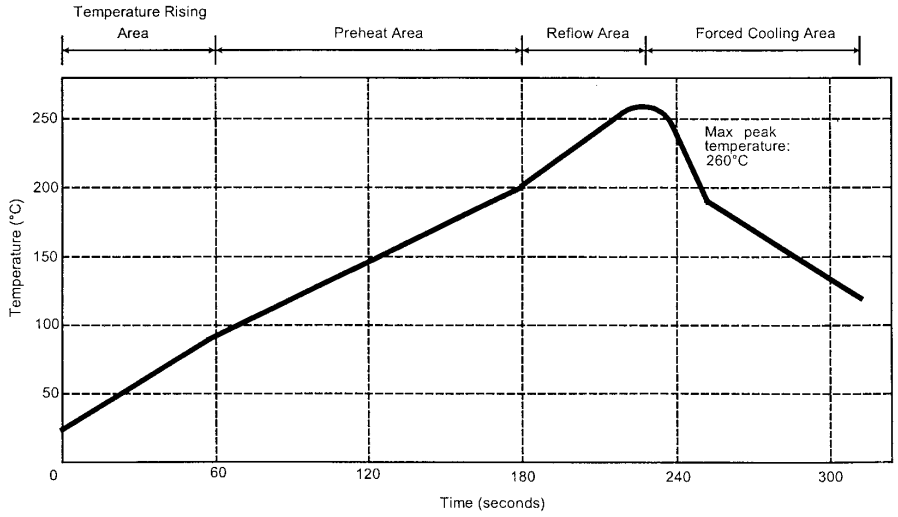
3. This process of soldering has been tested with a convection oven.
   Below please find the typical soldering profile to use.

4. Optional cleaning of printed circuit board.

5. Check solder joints and position of the component by visual inspection.

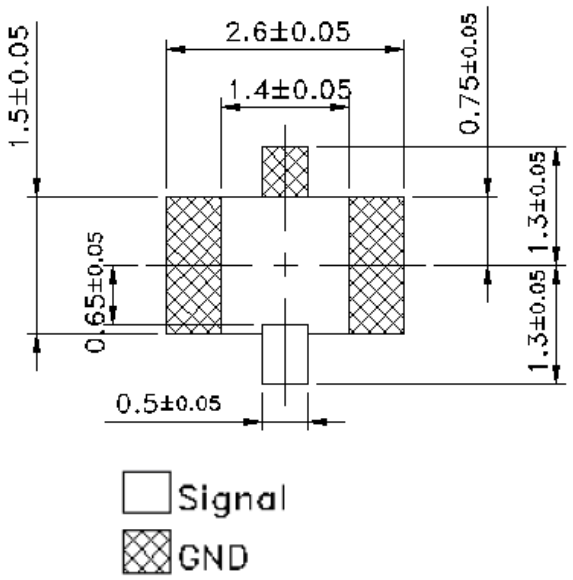
Note: When soldering a receptacle, no plug should be mated to the receptacle before completion of this procedure.

TEMPERATURE PROFILE



Parameter	Value	Unit
Temperature rising Area	1 to 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to - 4	°C/sec
Max dwell time above 100°C	420	sec

RECOMMENDED PCB DIMENSIONS:



PACKAGE